

### Description

The SX50P03NF uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

### General Features

$V_{DS} = -30V$   $I_D = -50A$

$R_{DS(ON)} < 13m\Omega @ V_{GS} = -10V$

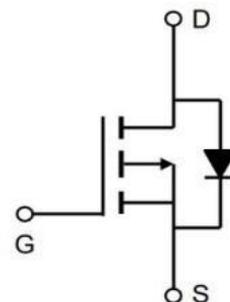
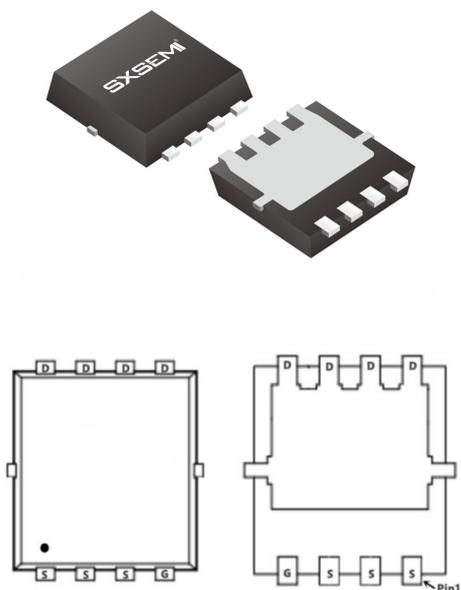
### Application

Lithium battery protection

Wireless impact

Mobile phone fast charging

### PDFN5\*6-8L



### Absolute Maximum Ratings ( $T_C = 25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-50	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-30	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	-150	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	125	mJ
$I_{AS}$	Avalanche Current	-50	A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation <sup>4</sup>	45	W
$P_D @ T_A = 25^\circ C$	Total Power Dissipation <sup>4</sup>	2.0	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	25	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	2.8	$^\circ C/W$

**Electrical Characteristics (T<sub>c</sub>=25°C unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA	-30	-33	---	V
ΔBVDSS/ΔT <sub>J</sub>	BVDSS Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =-1mA	---	-0.0232	---	V/°C
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-10V , I <sub>D</sub> =-30A	---	8.8	13	mΩ
		V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-15A	---	14	20	
VGS(th)	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	-1.0	-1.7	-2.5	V
ΔVGS(th)	V <sub>GS(th)</sub> Temperature Coefficient		---	4.6	---	mV/°C
IDSS	Drain-Source Leakage Current	V <sub>DS</sub> =-24V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	---	---	-1	uA
		V <sub>DS</sub> =-24V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C	---	---	-5	
IGSS	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V	---	---	±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =-5V , I <sub>D</sub> =-30A	---	30	---	S
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz	---	9	---	Ω
Q <sub>g</sub>	Total Gate Charge (-4.5V)	V <sub>DS</sub> =-15V , V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-15A	---	22	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	8.7	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	7.2	---	
Td(on)	Turn-On Delay Time	V <sub>DD</sub> =-15V , V <sub>GS</sub> =-10V , R <sub>G</sub> =3.3Ω I <sub>D</sub> =-15A	---	8	---	ns
T <sub>r</sub>	Rise Time		---	73.7	---	
Td(off)	Turn-Off Delay Time		---	61.8	---	
T <sub>f</sub>	Fall Time		---	24.4	---	
Ciss	Input Capacitance	V <sub>DS</sub> =-15V , V <sub>GS</sub> =0V , f=1MHz	---	2215	---	pF
Coss	Output Capacitance		---	310	---	
Crss	Reverse Transfer Capacitance		---	237	---	
IS	Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	---	---	-45	A
ISM	Pulsed Source Current <sup>2,5</sup>		---	---	-150	A
VSD	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =-1A , T <sub>J</sub> =25°C	---	---	-1	V
trr	Reverse Recovery Time	IF=-15A , dI/dt= 100A/μs , T <sub>J</sub> =25°C	---	19	---	nS
Q <sub>rr</sub>	Reverse Recovery Charge		---	9	---	nC

**Note :**

- 1、 The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width .The EAS data shows Max. rating .
- 3、 The power dissipation is limited by 175°C junction temperature
- 4、 EAS condition: T<sub>J</sub>=25°C , V<sub>DD</sub>= -24V, V<sub>G</sub>= -10V, R<sub>G</sub>=7Ω, L=0.1mH, I<sub>AS</sub>= -50A
- 5、 The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

Typical Characteristics

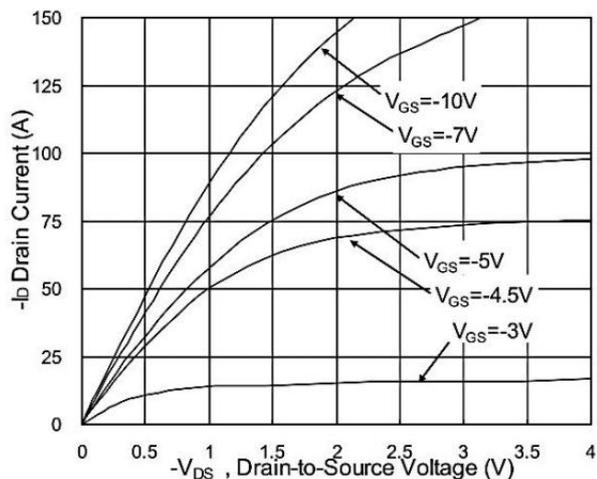


Fig.1 Typical Output Characteristics

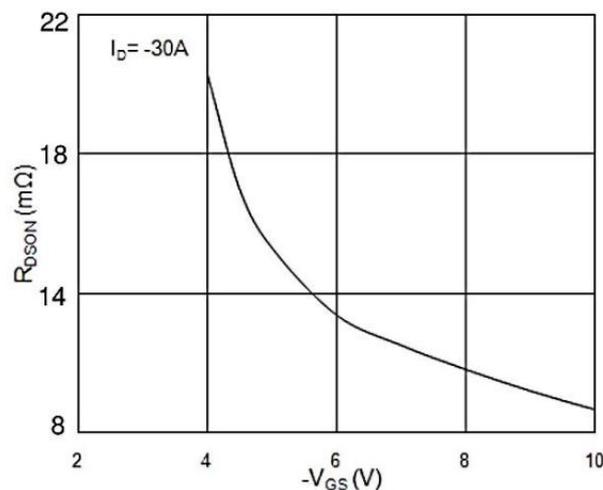


Fig.2 On-Resistance vs. G-S Voltage

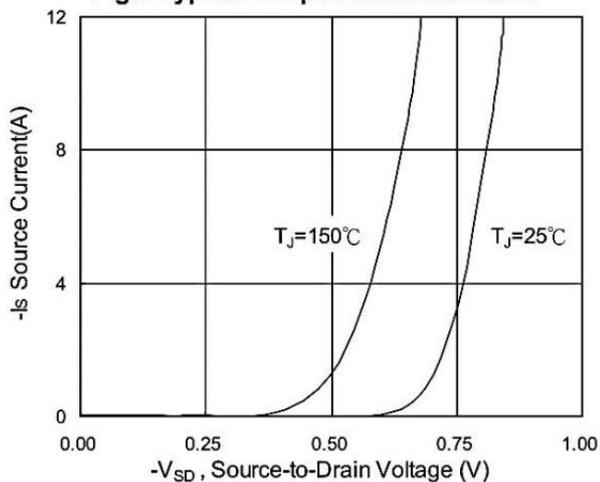


Fig.3 Forward Characteristics of Reverse

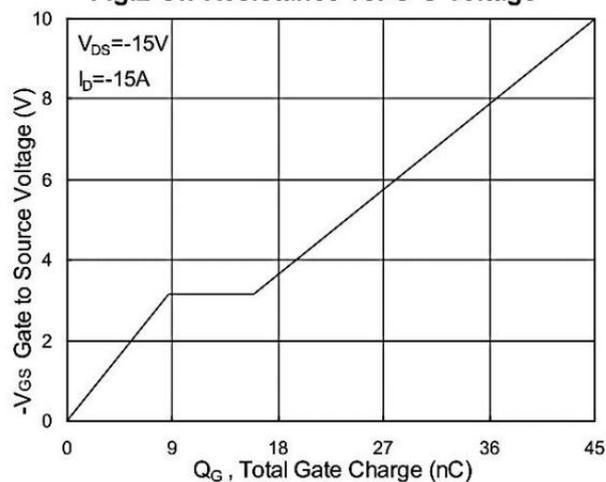


Fig.4 Gate-Charge Characteristics

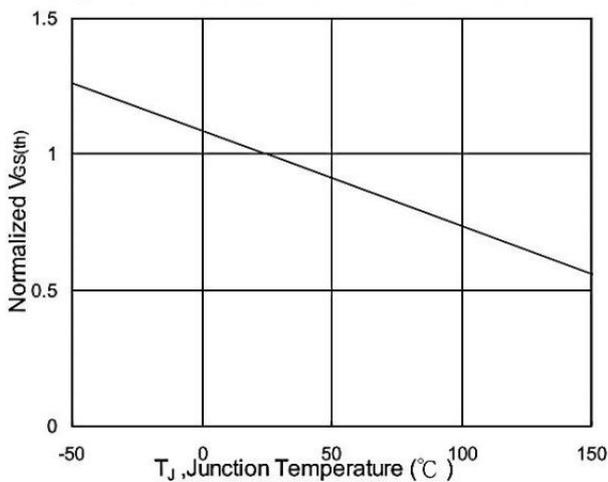


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

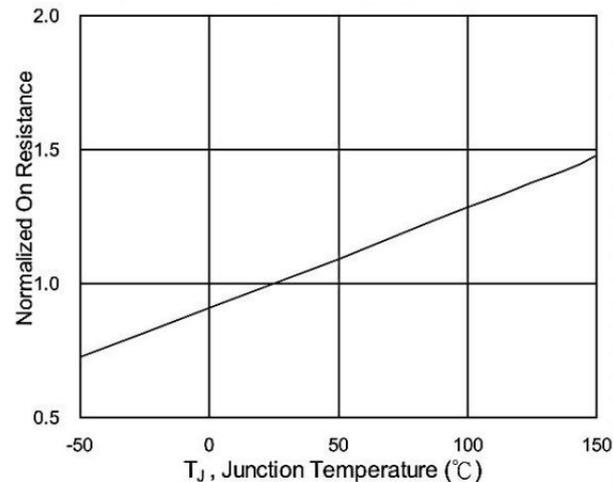


Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$

Typical Characteristics

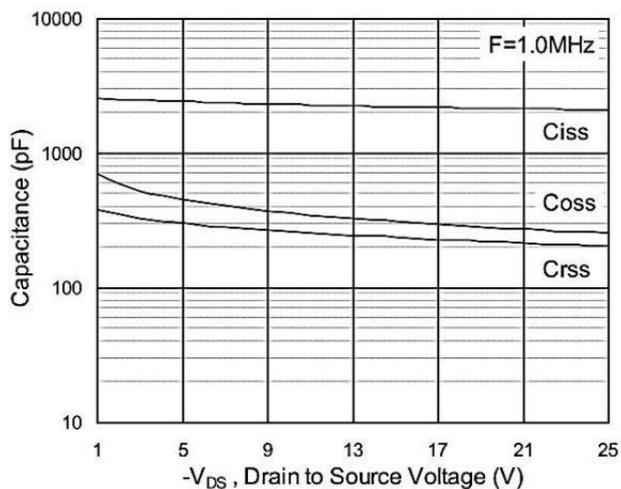


Fig.7 Capacitance

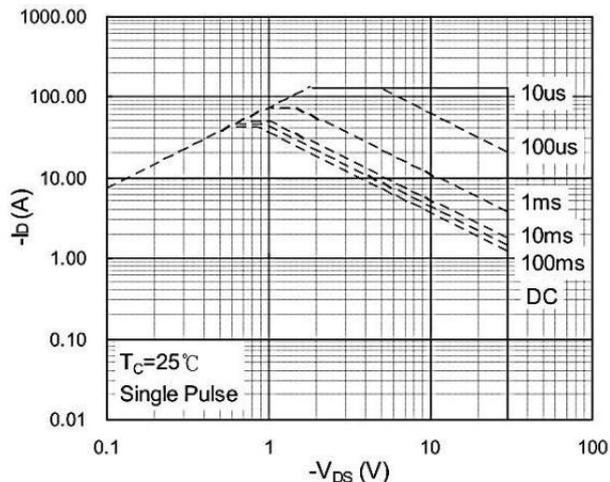


Fig.8 Safe Operating Area

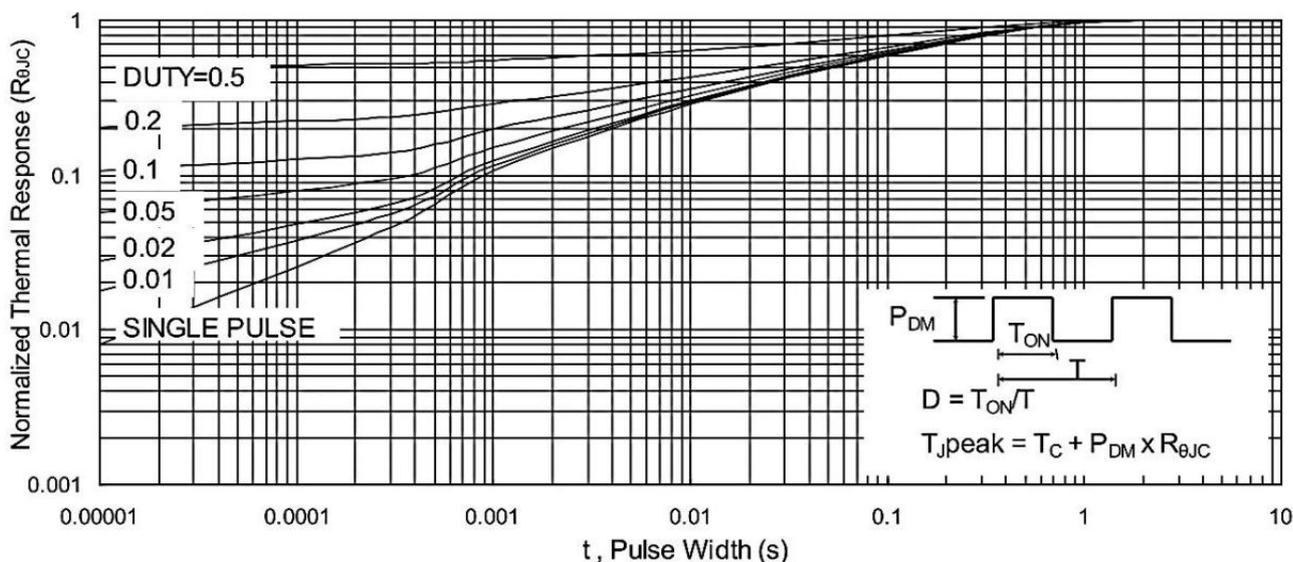


Fig.9 Normalized Maximum Transient Thermal Impedance

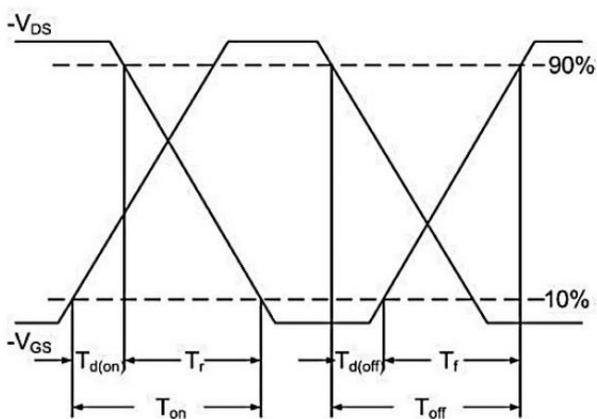


Fig.10 Switching Time Waveform

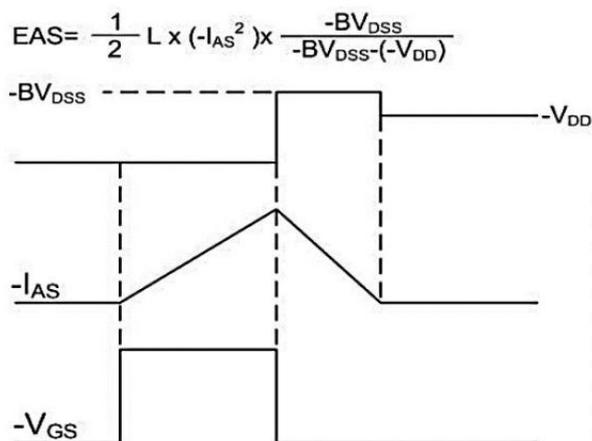
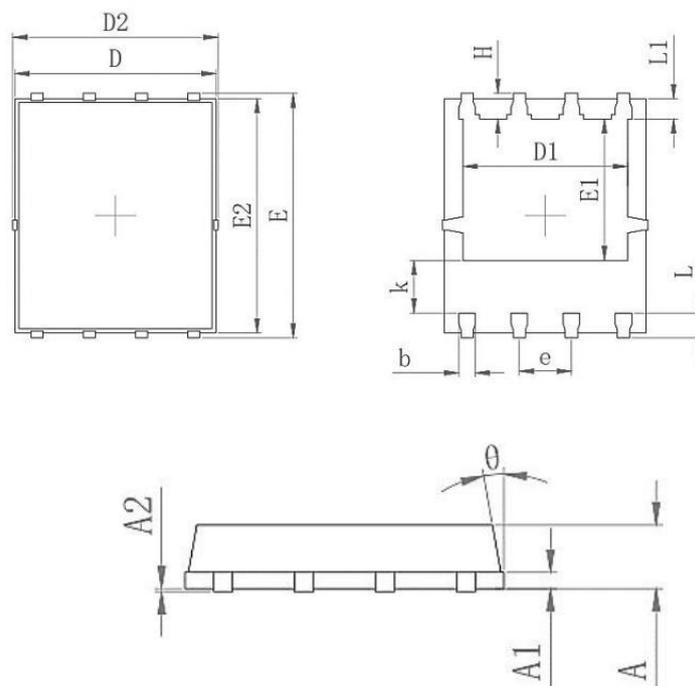


Fig.11 Unclamped Inductive Switching Waveform

**Package Mechanical Data-PDFN5\*6-8L-JQ Single**



Symbol	Common	
	mm	
	Mim	Max
A	0.900	1.100
A1	0.254	
A2	0-0.05	
D	4.824	4.976
D1	3.910	4.110
D2	4.944	5.076
E	5.924	6.076
E1	3.375	3.575
E2	5.674	5.826
b	0.350	0.450
e	1.270	
L	0.534	0.686
L1	0.424	0.576
K	1.190	1.390
H	0.549	0.701
	8°	12°

**Package Marking and Ordering Information**

Product ID	Pack	Marking	Qty(PCS)
TAPING	PDFN5*6-8L		5000